

Date Created : 2009/07/29  
Date Issued On : 2009/08/06  
PCN# : Q3093101

DESIGN/PROCESS CHANGE NOTIFICATION -- FINAL

This is to inform you that a design and/or process change will be made to the following product(s). This notification is for your information and concurrence.

If you require data or samples to qualify this change, please contact **Fairchild Semiconductor within 30 days of receipt of this notification.**

Updated process quality documentation, such as FMEAs and Control Plans, are available for viewing upon request.

If you have any questions concerning this change, please contact:

Technical Contact:

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PCN Originator:

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Implementation of change:

Expected 1st Device Shipment Date: 2009/11/05

Earliest Year/Work Week of Changed Product: 0932

Change Type Description: Alternate Assembly Site Location / Qualification, Alternate Fab Location

Description of Change (From): The wafer fabrication is currently performed at the Fairchild Semiconductor South Portland Maine 150mm line. The WLCSP (wafer level chip scale package) solder bump process is currently performed at the Amkor Technology Korea K4 site. The WLCSP backside laminate and die processing is currently performed at the Amkor Technology Taiwan T3 site.

Description of Change (To): Wafer fabrication at the Fairchild Semiconductor South Portland Maine 200mm line or 150mm line. WLCSP solder bump at the Fairchild Semiconductor South Portland Maine CSP facility or the Amkor Technology Korea K4 facility. WLCSP backside laminate and die processing at the Fairchild Semiconductor Penang Malaysia facility or Amkor Technology T3 facility.

Reason for Change : To allow dual sourcing to support growing demand for the FSA9480UCX.

Qual/REL Plan Numbers : Q20090452

Qualification :

-Reliability environmental & mechanical stress tests on alternate sourced devices successfully met requirements. Board Level tests on devices run in the Fairchild Semiconductor South Portland Maine CSP facility passed JESD22 standards. Characterization results are comparable to current process devices.

**Results/Discussion for Qual Plan Number Q20090452**

Test: (Autoclave)   Conditions: 100%RH, 121C   Standard: JESD22-A102					
Lot	Device	96-HOURS	Failure Code		
Q20090452AAACL	FSA9480UCX	0/77			
Q20090452ABACL	FSA9480UCX	0/77			
Q20090452ACACL	FSA9480UCX	0/77			

  

Test: (High Temperature Storage Life)   Conditions: 150C   Standard: JESD22-A103					
Lot	Device	168-HOURS	500-HOURS	1000-HOURS	Failure Code
Q20090452AAHTSL	FSA9480UCX	0/77			
			0/77		
				0/77	
Q20090452ABHTSL		0/77			
			0/77		
				0/77	
Q20090452ACHTSL		0/77			
			0/77		
				0/77	

  

Test: (Highly Accelerated Stress Test)   Conditions: 85%RH, 130C, 0V   Standard: JESD22-A110				
Lot	Device	96-HOURS	Failure Code	
Q20090452AAHAST1	FSA9480UCX	0/45		
Q20090452ABHAST1	FSA9480UCX	0/45		
Q20090452ACHAST1	FSA9480UCX	0/45		

  

Test: (Physical Dimensions)   Conditions:   Standard: JESD22-B100			
Lot	Device	Results	Failure Code
Q20090452AAPHYD	FSA9480UCX	0/5	
Q20090452ABPHYD	FSA9480UCX	0/5	
Q20090452ACPHYD	FSA9480UCX	0/5	

  

Test: (Static Op Life)   Conditions: 150C, 0V   Standard: JESD22-A108					
Lot	Device	168-HOURS	500-HOURS	1000-HOURS	Failure Code
Q20090452AASOPL1		0/77			
			0/77		
				0/77	
Q20090452ABSOP1		0/77			
			0/77		
				0/77	
Q20090452ACSOPL1		0/77			
			0/77		
				0/77	

  

Test: (Temperature Cycle)   Conditions: -40C, 125C   Standard: JESD22-A104				
Lot	Device	500-CYCLES	1000-CYCLES	Failure Code
Q20090452AATMCL2	FSA9480UCX	0/77		
Q20090452AATMCL2	FSA9480UCX		0/77	
Q20090452ABTMCL2	FSA9480UCX	0/77		
Q20090452ABTMCL2	FSA9480UCX		0/77	
Q20090452ACTMCL2	FSA9480UCX	0/77		
Q20090452ACTMCL2	FSA9480UCX		0/77	

Product Id Description : USB2.0 Accessory Switch in 25 lead WLCSP

Affected FSIDs :

FSA9480UCX		
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